



The BTM510 and BTM511 are low-power Bluetooth® modules from Laird Technologies are designed for adding robust audio and voice capabilities. Based on the market-leading Cambridge Silicon Radio BC05 chipset, these modules provide exceptionally low power consumption with outstanding range. Supporting the latest Bluetooth Version 2.1+EDR specification, these modules provide the important advantage of secure simple pairing that improves security and enhances easy use. BTM510 and BTM511 modules now come standard with the apt-X™ audio codec for wireline quality stereo audio.

The compact size of the modules makes them ideal for battery-powered or headset form factor audio and voice devices. With a 16-bit stereo codec and microphone inputs to support both stereo and mono applications, these modules also contain a fully, integrated Bluetooth-qualified stack along with SPP, HFP 1.5, HSP, AVRCP, DUN, and A2DP profiles.

The BTM510/511 modules include an embedded 32-bit, 64-MIPS DSP core within the BC05. This allows designers to add significant product enhancements including features such as echo cancellation, noise reduction, and audio enhancement using additional soft codecs.

BTM510 and BTM511 modules are provided with CSR's apt-X codec without additional license fees. CSR's world renowned apt-X™ audio compression solutions retain the full integrity of original digital audio and are optimized for instant real-time audio streaming (<http://www.csr.com/products/technology/aptx>).

To speed product development and integration, Laird Technologies has developed a comprehensive AT command interface that simplifies application development, including support for audio and headset functionality. Combined with a low-cost development kit, Laird Technologies' Bluetooth modules provide faster time to market.

FEATURES

- Fully featured Bluetooth multimedia chipset
- Bluetooth v2.1+EDR
- Supports mono and stereo headset applications
- apt-X Audio Codec provided free of charge
- Adaptive frequency hopping to cope with interference from other wireless devices
- 32-bit Kalimba DSP for enhanced audio applications
- Support for secure simple pairing
- External or internal antenna options
- HSP, HFP, A2DP, and AVRCP audio profiles
- 16-bit stereo codec
- AAC: decoder only; Aptx and SBC: both encoder and decoder (source and sink)
- CVC audio enhancement supported
- EIR fully supported
- Integrated audio amplifiers for driving stereo speaker
- Comprehensive AT interface for simple programming
- Bluetooth End Product qualified
- Compact size
- Class 2 output – 4 dBm
- Low power operation
- WLAN co-existence hardware support

APPLICATION AREAS

- High-quality stereo headsets
- Mono voice headsets
- Hands-free devices
- Wireless audio cable replacement
- MP3 and music players
- Phone accessories
- VoIP products
- Cordless headsets
- Aftermarket automotive applications

global solutions: local support.™

USA: +1.800.492.2320

Europe: +44.1628.858.940

Asia: +852.2268.6567

wirelessinfo@lairdtech.com

www.lairdtech.com/wireless

CATEGORIES	FEATURE	IMPLEMENTATION	
Wireless Specification	Bluetooth®	Version 2.1+EDR	
	Frequency	2.402 – 2.480 GHz	
	Max Transmit Power	Class 2 4 dBm (at antenna pad – BTM510) 4 dBm (from integrated antenna – BTM511)	
	Receive Sensitivity	Better than -86 dBm	
	Range	30 meters	
	Data Rates	Up to 3 Mbps (over the air)	
	UART Data Transfer Rate	Greater than 300 Kbps	
Host Interface	UART	Supports DTR, DSR, DCD and RI, multiplexed with other functionality.	
Audio Interfaces	Codec	Internal 16 bit Stereo Codec Integrated Amplifiers for driving Stereo Speaker	
	I2S / PCM	Master / Slave roles	
	Microphone	Stereo microphone input	
DSP	Integrated Kalimba DSP	32-bit, 64 MIPS	
Additional I/O	4 x GPIO	Function Mapping e.g. button control	
Profiles		SPP – Serial Port Profile HSP HFP – Audio Gateway and Handset A2DP – Source and Sink AVRCP – Target and Controller DUN	
	Supply Voltage	Supply	3.0 V – 3.6 V DC
		I/O	1.7 V – 3.6 V DC
	Power Consumption	Current Consumption	Operational - Less than 70 mA (including speaker amplifiers) Idle (sleep) < 1.0 mA
	Coexistence / Compatibility	802.11 (WLAN)	2 wire and 3 wire schemes supported
Connections	External Antenna	Connection via SMT pad – BTM510	
	Internal Antenna	Multilayer ceramic antenna – BTM511	
Programming API		AT Command Set (extended for audio and headset functions)	
Physical	Dimensions	14.0 mm x 20.0 mm x 3.4 mm (integrated antenna – BTM510)	
		14.0 mm x 25.0 mm x 3.4 mm (integrated antenna – BTM511)	
Environmental	Operating Temperature	-30°C to +70°C	
	Storage Temperature	-40°C to +85°C	
Miscellaneous	Lead free	Lead-free and RoHS compliant	
	Warranty	1 Year	
Development Tools	Development Kit	Development board and software tools	
Approvals	Bluetooth	End Product Approved	
	FCC/IC & CE	BTM510 - Limited Modular Approval BTM511 - Full Modular Approval	

ORDERING INFORMATION

BTM510	Bluetooth Multimedia Module (external antenna)
BTM511	Bluetooth Multimedia Module (with integrated antenna)
DVK- BTM510	Development Kit (external antenna)
DVK- BTM511	Development Kit (with integrated antenna)

The details contained within the document are subject to change. Download the product specification from www.lairdtech.com/wireless for the most current specification.

LWS-DS-BTM510-511 0412

Any information furnished by Laird Technologies, Inc. and its agents is believed to be accurate and reliable. All specifications are subject to change without notice. Responsibility for the use and application of Laird Technologies materials rests with the end user, since Laird Technologies and its agents cannot be aware of all potential uses. Laird Technologies makes no warranties as to the fitness, merchantability or suitability of any Laird Technologies materials or products for any specific or general uses. Laird Technologies shall not be liable for incidental or consequential damages of any kind. All Laird Technologies products are sold pursuant to the Laird Technologies Terms and Conditions of sale in effect from time to time, a copy of which will be furnished upon request. © Copyright 2012 Laird Technologies, Inc. All Rights Reserved. Laird, Laird Technologies, the Laird Technologies Logo, and other marks are trade marks or registered trade marks of Laird Technologies, Inc. or an affiliate company thereof. Other product or service names may be the property of third parties. Nothing herein provides a license under any Laird Technologies or any third party intellectual property rights.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for [Bluetooth / 802.15.1 Development Tools](#) category:

Click to view products by [Laird Connectivity](#) manufacturer:

Other Similar products are found below :

[DA14580PRODTLKT](#) [BCM92073X_LE_KIT](#) [1628](#) [CYBLE-224116-EVAL](#) [450-0185](#) [MIKROE-2471](#) [BLE-IOT-GEVB](#) [450-0184](#) [DVK-BT830-SA-01](#) [MIKROE-2399](#) [EKSHCNZXZ](#) [EVAL-BT](#) [EBSGJNZWY](#) [DEMOBOARD-T7024PGM](#) [STEVAL-IDB005V1D](#) [STEVAL-IDB001V1](#) [SP14808](#) [MIKROE-2545](#) [EBSHJNZXZ](#) [EKSGJNZWY](#) [EKSHJNZXZ](#) [CYBLE-212019-EVAL](#) [ABBTM-2.4GHZ-EVAL](#) [2746](#) [AFERO-DB-01](#) [ATBTLC1000-XPRO](#) [ATBTLC1000-XSTK](#) [CYBLE-202007-EVAL](#) [BCM9WICED_SENSE2](#) [CY5674](#) [CY5676](#) [CY5676A](#) [CY8CKIT-042-BLE](#) [CY8CKIT-042-BLE-A](#) [CY8CKIT-141](#) [CY8CKIT-142](#) [CY8CKIT-143A](#) [CYBLE-022001-EVAL](#) [CYBLE-224110-EVAL](#) [410-214](#) [EBSHSNZWZ](#) [EKSHSNZWZ](#) [BA600](#) [BB600](#) [BC600](#) [DVK-BL652-SA](#) [DVK-BL652-SC](#) [DVK-BT730-SA](#) [DVK-BT730-SC](#) [DVK-BT740-SA](#)